

Title (en)
Electrolyte for electroless gold plating

Title (de)
Elektrolyt für eine reduktive Goldabscheidung

Title (fr)
Electrolyte pour le dépôt non-électrolytique d'or

Publication
EP 0853139 B1 20011010 (DE)

Application
EP 97121804 A 19971211

Priority
DE 19651900 A 19961213

Abstract (en)
[origin: EP0853139A1] A novel reductive gold plating bath electrolyte contains 0.1-20 g/l potassium, sodium or ammonium gold(I) cyanide or gold(III) cyanide, 0.1-25 g/l free potassium, sodium or ammonium cyanide, 0.1-50 g/l potassium, sodium or ammonium sulphite, 0.01-10 g/l aromatic nitro compound, 1-100 g/l free alkali, 1-50 g/l complex former(s) selected from hydroxycarboxylic acids, phosphonic acids, nitriloacetic acids and ethylene diamine-acetic acids and 0.1-50 g/l borane and/or boranate reducing agent. Also claimed is a reductive gold plating process employing the above electrolyte, preferably at 60-95 (especially 75-85) degrees C.

IPC 1-7
C23C 18/44

IPC 8 full level
C23C 18/44 (2006.01)

CPC (source: EP)
C23C 18/44 (2013.01)

Designated contracting state (EPC)
DE FR GB IT

DOCDB simple family (publication)
DE 19651900 A1 19980618; DE 59704863 D1 20011115; EP 0853139 A1 19980715; EP 0853139 B1 20011010

DOCDB simple family (application)
DE 19651900 A 19961213; DE 59704863 T 19971211; EP 97121804 A 19971211